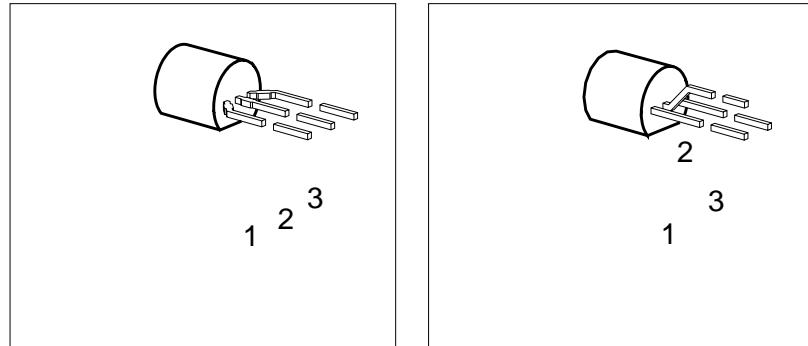


## SIPMOS® Small-Signal Transistor

BSS 149

- $V_{DS}$  200 V
- $I_D$  0.35 A
- $R_{DS(on)}$  3.5 Ω
- N channel
- Depletion mode
- High dynamic resistance
- Available grouped in  $V_{GS(th)}$



Type	Ordering Code	Tape and Reel Information	Pin Configuration			Marking	Package
			1	2	3		
BSS 149	Q62702-S623	bulk	G	D	S	SS149	TO-92
BSS 149	Q67000-S252	E6325: 2000 pcs/carton; Ammopack					

### Maximum Ratings

Parameter	Symbol	Values	Unit
Drain-source voltage	$V_{DS}$	200	V
Drain-gate voltage, $R_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	200	
Gate-source voltage	$V_{GS}$	$\pm 20$	
ESD Sensitivity (HBM) as per MIL-STD 883	—	Class 1	
Continuous drain current, $T_A = 34^\circ\text{C}$	$I_D$	0.35	A
Pulsed drain current, $T_A = 25^\circ\text{C}$	$I_{D \text{ puls}}$	1.05	
Max. power dissipation, $T_A = 25^\circ\text{C}$	$P_{\text{tot}}$	1.0	W
Operating and storage temperature range	$T_j, T_{\text{stg}}$	$-55 \dots +150$	°C

Thermal resistance, chip-ambient (without heat sink)	$R_{\text{thJA}}$	$\leq 125$	K/W
DIN humidity category, DIN 40 040	—	E	—
IEC climatic category, DIN IEC 68-1	—	55/150/56	

## Electrical Characteristics

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

## Static Characteristics

Drain-source breakdown voltage $V_{GS} = -3\text{ V}$ , $I_D = 0.25\text{ mA}$	$V_{(\text{BR})DSS}$	200	—	—	V
Gate threshold voltage $V_{DS} = 3\text{ V}$ , $I_D = 1\text{ mA}$	$V_{GS(\text{th})}$	— 1.8	— 1.2	— 0.7	
Drain-source cutoff current $V_{DS} = 200\text{ V}$ , $V_{GS} = -3\text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	$I_{DSS}$	—	—	0.2 200	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}$ , $V_{DS} = 0$	$I_{GSS}$	—	10	100	nA
Drain-source on-resistance $V_{GS} = 0\text{ V}$ , $I_D = 0.05\text{ A}$	$R_{DS(\text{on})}$	—	2.5	3.5	$\Omega$

## Dynamic Characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}$ , $I_D = 0.35\text{ A}$	$g_{fs}$	0.4	0.6	—	S
Input capacitance $V_{GS} = 0$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{iss}$	—	500	670	pF
Output capacitance $V_{GS} = 0$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{oss}$	—	40	60	
Reverse transfer capacitance $V_{GS} = 0$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{rss}$	—	12	20	
Turn-on time $t_{on}$ , ( $t_{on} = t_{d(on)} + t_f$ ) $V_{DD} = 30\text{ V}$ , $V_{GS} = -2\text{ V} \dots + 5\text{ V}$ , $R_{GS} = 50\text{ }\Omega$ , $I_D = 0.29\text{ A}$	$t_{d(on)}$ $t_f$	— —	7 20	10 30	ns
Turn-off time $t_{off}$ , ( $t_{off} = t_{d(off)} + t_f$ ) $V_{DD} = 30\text{ V}$ , $V_{GS} = -2\text{ V} \dots + 5\text{ V}$ , $R_{GS} = 50\text{ }\Omega$ , $I_D = 0.29\text{ A}$	$t_{d(off)}$ $t_f$	— —	60 50	80 65	

### Electrical Characteristics (cont'd)

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Continuous reverse drain current $T_A = 25^\circ\text{C}$	$I_S$	—	—	0.35	A
Pulsed reverse drain current $T_A = 25^\circ\text{C}$	$I_{SM}$	—	—	1.05	
Diode forward on-voltage $I_F = 0.7 \text{ A}, V_{GS} = 0$	$V_{SD}$	—	0.8	1.2	V

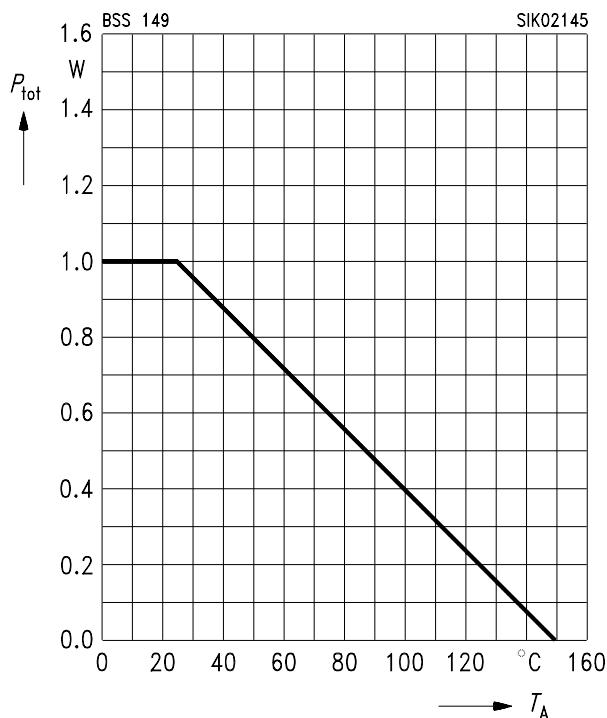
$V_{GS(\text{th})}$ Grouping	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Range of $V_{GS(\text{th})}$	$\Delta V_{GS(\text{th})}$	—	0.15	V	—
Threshold voltage selected in groups <sup>1)</sup> :	$V_{GS(\text{th})}$				$V_{DS1} = 0.2 \text{ V}$ $V_{DS2} = 3 \text{ V};$ $I_D = 1 \text{ mA}$
P		— 0.95	— 0.80	V	
R		— 1.08	— 0.93	V	
S		— 1.21	— 1.06	V	
T		— 1.34	— 1.19	V	
U		— 1.47	— 1.32	V	
V		— 1.60	— 1.45	V	
W		— 1.73	— 1.58	V	

- 1) A specific group cannot be ordered separately.  
Each reel only contains transistors from one group.

## Characteristics

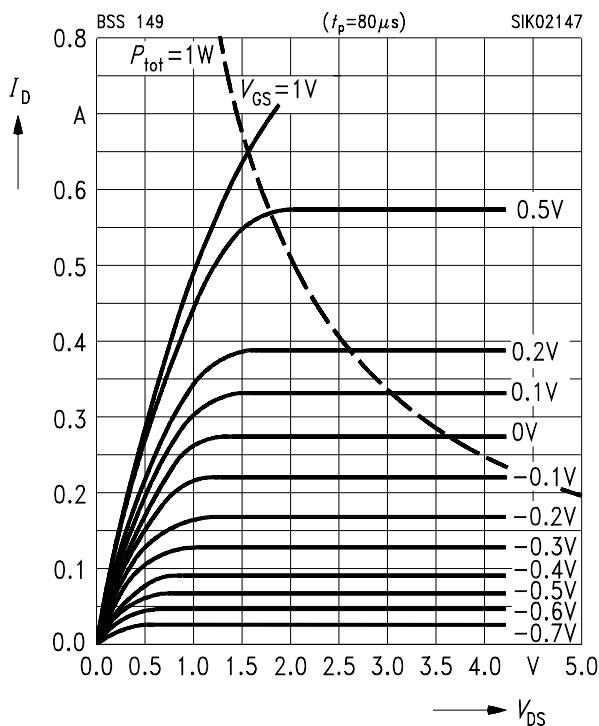
at  $T_j = 25^\circ\text{C}$ , unless otherwise specified.

**Total power dissipation**  $P_{\text{tot}} = f(T_A)$



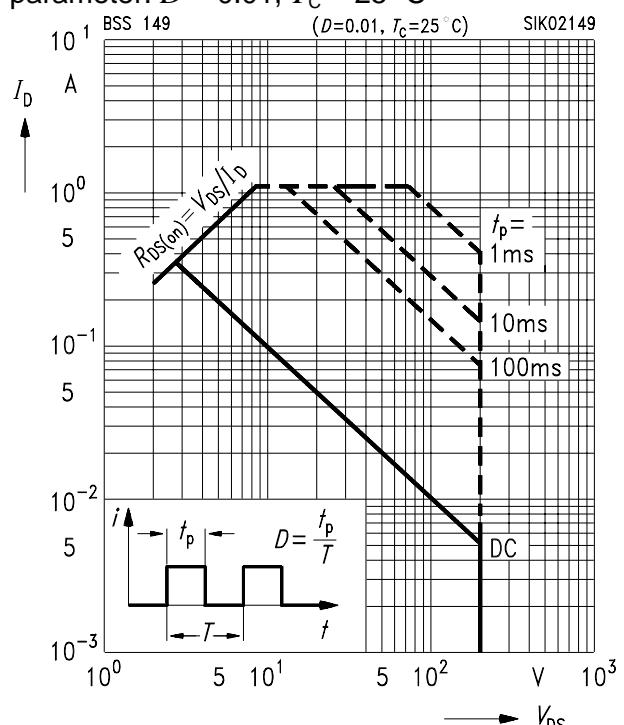
**Typ. output characteristics**  $I_D = f(V_{DS})$

parameter:  $t_p = 80 \mu\text{s}$



**Safe operating area**  $I_D = f(V_{DS})$

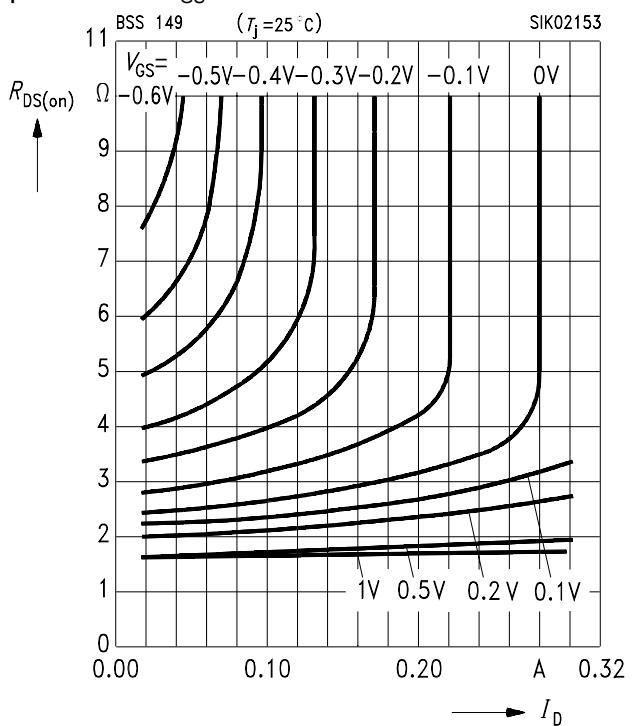
parameter:  $D = 0.01, T_C = 25^\circ\text{C}$



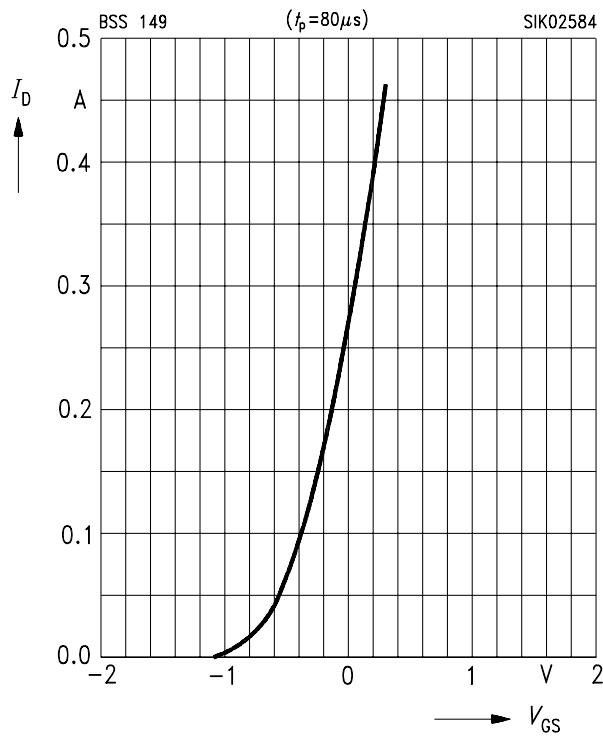
**Typ. drain-source on-resistance**

$R_{DS(on)} = f(I_D)$

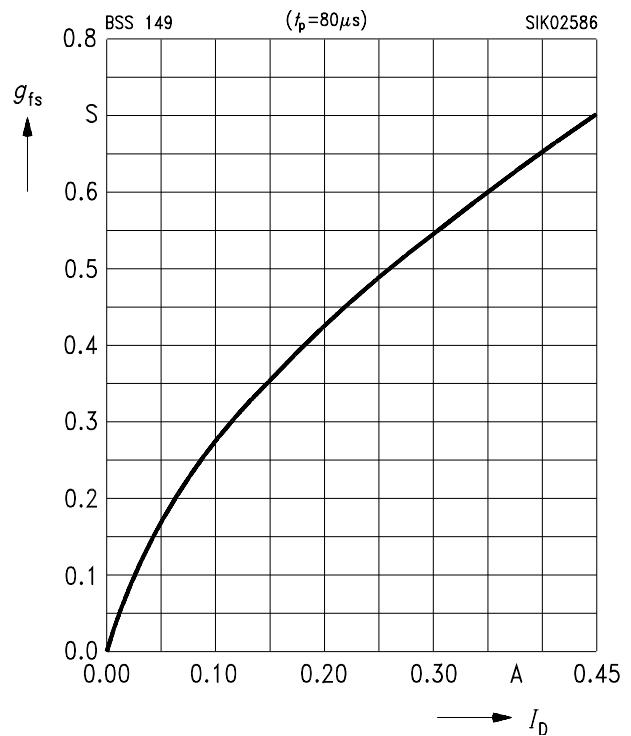
parameter:  $V_{GS}$



**Typ. transfer characteristics  $I_D = f(V_{GS})$**   
 parameter:  $t_p = 80 \mu\text{s}$ ,  $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max.}}$

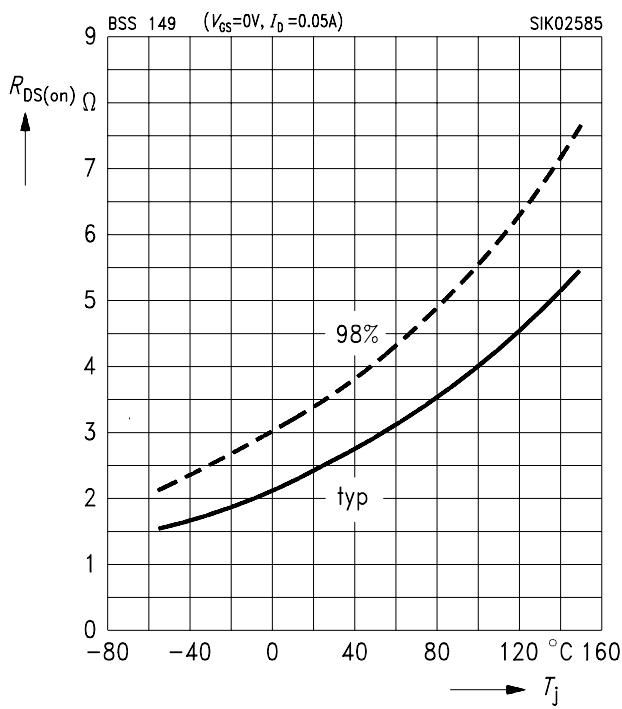


**Typ. forward transconductance  $g_{fs} = f(I_D)$**   
 parameter:  $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max.}}$ ,  $t_p = 80 \mu\text{s}$

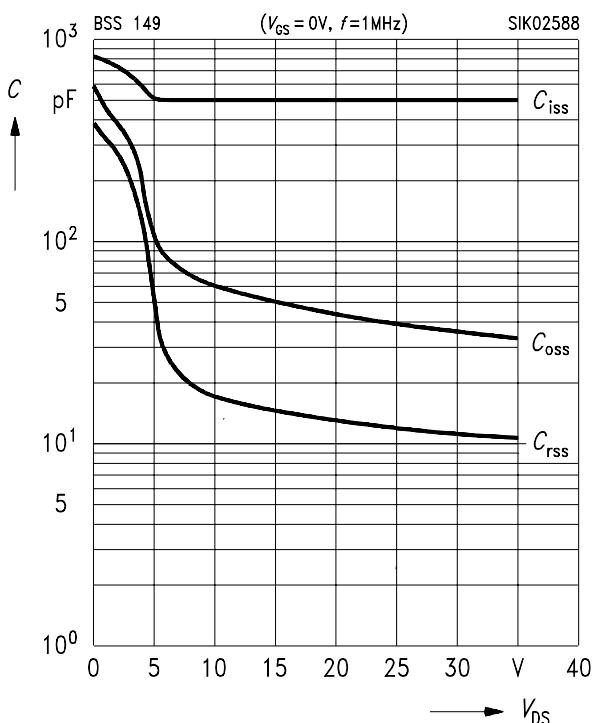


#### Drain-source on-resistance

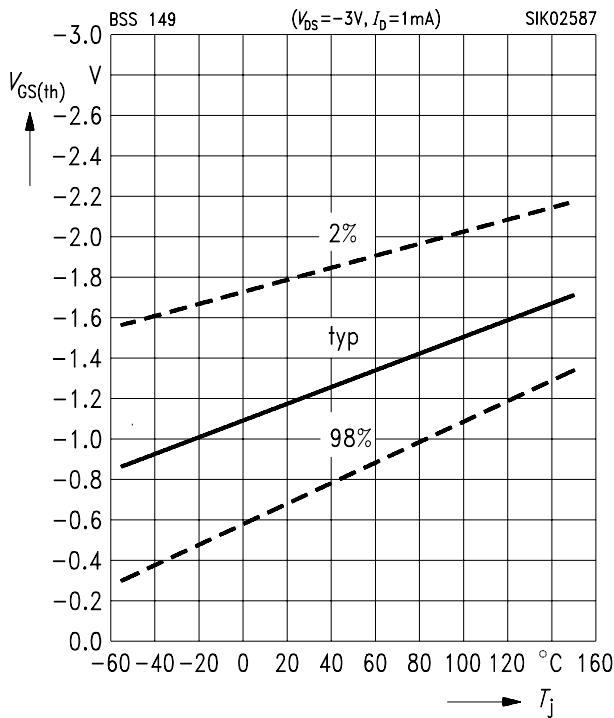
$R_{DS(\text{on})} = f(T_j)$   
 parameter:  $I_D = 0.05 \text{ A}$ ,  $V_{GS} = 0 \text{ V}$ , (spread)



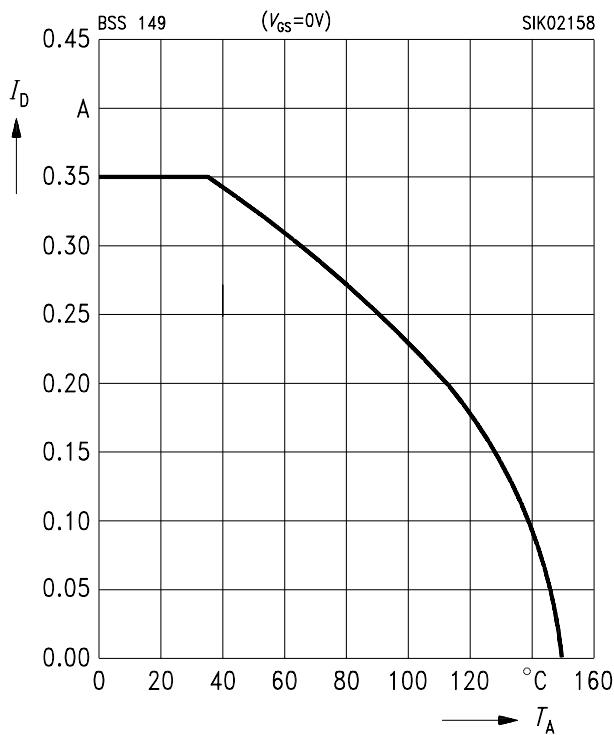
**Typ. capacitances  $C = f(V_{DS})$**   
 parameter:  $V_{GS} = 0$ ,  $f = 1 \text{ MHz}$



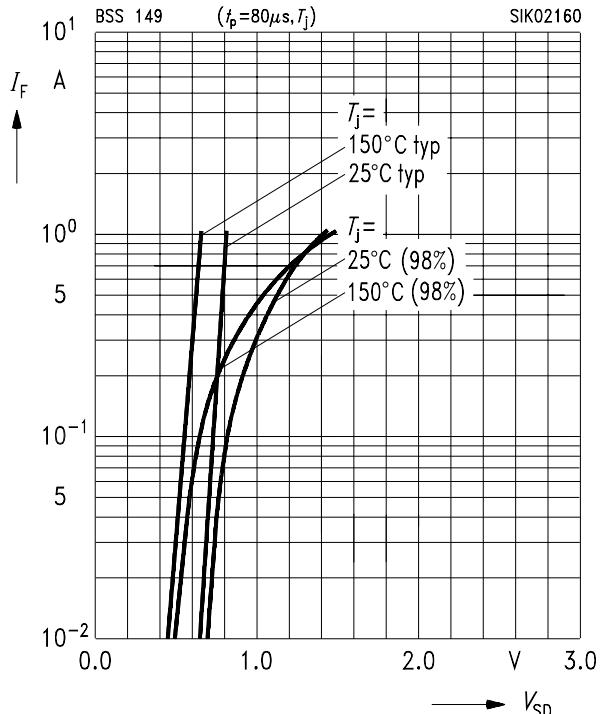
**Gate threshold voltage**  $V_{GS(th)} = f(T_j)$   
 parameter:  $V_{DS} = 3 \text{ V}$ ,  $I_D = 1 \text{ mA}$ , (spread)



**Drain current**  $I_D = f(T_A)$   
 parameter:  $V_{GS} \geq 3 \text{ V}$



**Forward characteristics of reverse diode**  
 $I_F = f(V_{SD})$   
 parameter:  $t_p = 80 \mu\text{s}$ ,  $T_j$ , (spread)



**Drain-source breakdown voltage**  
 $V_{(BR)DSS} = b \times V_{(BR)DSS} (25 \text{ }^\circ\text{C})$

